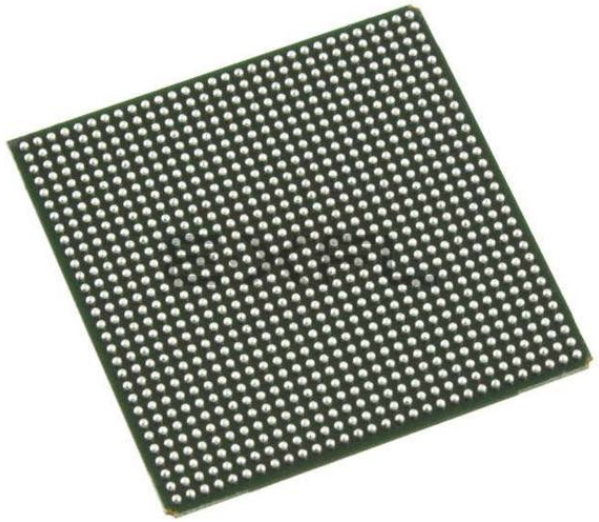
Lattice Semiconductor Corporation - LFSCM3GA15EP1-5FN900C Datasheet



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The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	3750
Number of Logic Elements/Cells	15000
Total RAM Bits	1054720
Number of I/O	300
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FPBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga15ep1-5fn900c

LatticeSC/M Family Data Sheet Architecture

December 2008 **Data Sheet DS1004**

Architecture Overview

The LatticeSC architecture contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM Embedded Block RAM (EBR). The upper left and upper right corners of the devices contain SERDES blocks and their associated PCS blocks, as show in Figure 2-1.

Top left and top right corner of the device contain blocks of SERDES. Each block of SERDES contains four channels (quad). Each channel contains a single serializer and de-serializer, synchronization and word alignment logic. The SERDES quad connects with the Physical Coding Sub-layer (PCS) blocks that contain logic to simultaneously perform alignment, coding, de-coding and other functions. The SERDES quad block has separate supply, ground and reference voltage pins.

The PICs contain logic to facilitate the conditioning of signals to and from the I/O before they leave or enter the FPGA fabric. The block provides DDR and shift register capabilities that act as a gearbox between high speed I/O and the FPGA fabric. The blocks also contain programmable Adaptive Input Logic that adjusts the delay applied to signals as they enter the device to optimize setup and hold times and ensure robust performance.

sysMEM EBRs are large dedicated fast memory blocks. They can be configured as RAM, ROM or FIFO. These blocks have dedicated logic to simplify the implementation of FIFOs.

The PFU, PIC and EBR blocks are arranged in a two-dimensional grid with rows and columns as shown in Figure 2-1. These blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

The corners contain the sysCLOCK Analog Phase Locked Loop (PLL) and Delay Locked Loop (DLL) Blocks. The PLLs have multiply, divide and phase shifting capability; they are used to manage the phase relationship of the clocks. The LatticeSC architecture provides eight analog PLLs per device and 12 DLLs. The DLLs provide a simple delay capability and can also be used to calibrate other delays within the device.

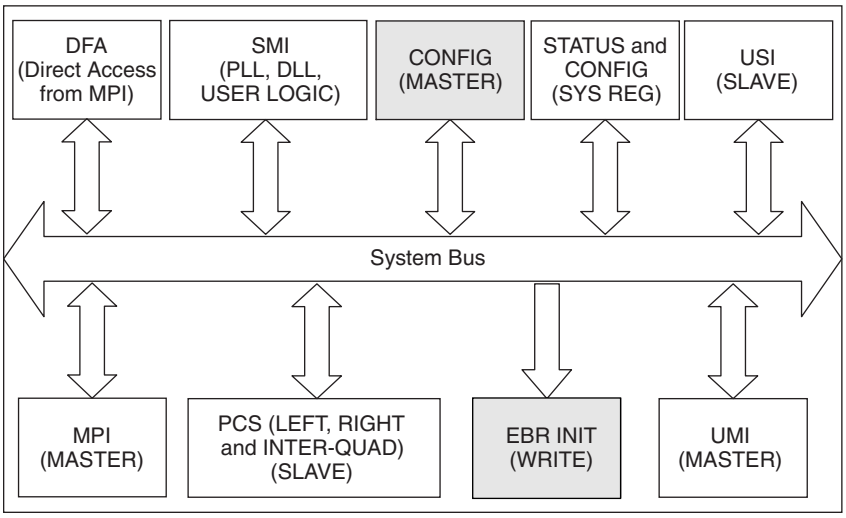
Every device in the family has a JTAG Port with internal Logic Analyzer (ispTRACY) capability. The sysCONFIG™ port which allows for serial or parallel device configuration. The system bus simplifies the connections of the external microprocessor to the device for tasks such as SERDES and PCS configuration or interface to the general FPGA logic. The LatticeSC devices use 1.2V as their core voltage operation with 1.0V operation also possible.

Table 2-9. Supported Input Standards

Input Standard	V_{REF} (Nom.)	V_{CCIO}[1] (Nom.)	On-chip Termination
Single Ended Interfaces			
LVTTL33[3]	—	3.3	None
LVCMOS 33, 25, 18, 15, 12[3]	—	3.3/2.5/1.8/1.5/1.2	None
PCI33, PCIX33, AGP1X33[3]	—	3.3	None
PCIX15	0.75	1.5[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
AGP2X33	1.32	—	None
HSTL18_I, II	0.9	1.8[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
HSTL18_III, IV	1.08	1.8[2]	None / V_{CCIO}: 50
HSTL15_I, II	0.75	1.5[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
HSTL15_III, IV	0.9	1.5[2]	None / V_{CCIO}: 50
SSTL33_I, II	1.5	3.3	None
SSTL25_I, II	1.25	2.5[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
SSTL18_I, II	0.9	1.8[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
GTL+, GTL	1.0 / 0.8	1.5 / 1.2[2]	None / V_{CCIO}: 50
Differential Interfaces			
SSTL18D_I, II	—	1.8[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
SSTL25D_I, II	—	2.5[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
SSTL33D_I, II	—	3.3	None
HSTL15D_I, II	—	1.5[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
HSTL18D_I, II	—	1.8[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
LVDS	—	—	None / Diff: 120, 150, 220, 240/ Diff to V_{CMT}: 120, 150, 220, 240
Mini-LVDS	—	—	None / Diff: 120, 150 / Diff to V_{CMT}: 120, 150
BLVDS25	—	—	None
MLVDS25	—	—	None
RSDS	—	—	None / Diff: 120, 150, 220, 240/ Diff to V_{CMT}: 120, 150, 220, 240
LVPECL33	—	≤2.5	None / Diff: 120, 150, 220, 240/ Diff to V_{CMT}: 120, 150, 220, 240

1. When not specified V_{CCIO} can be set anywhere in the valid operating range.
2. V_{CCIO} needed for on-chip termination to $V_{CCIO}/2$ or V_{CCIO} only. V_{CCIO} is not specified for off-chip termination or V_{TT} termination.
3. All ratioed input buffers and dedicated pin input buffers include hysteresis with a typical value of 50mV.

Figure 2-31. LatticeSC System Bus Interfaces



Several interfaces exist between the System Bus and other FPGA elements. The MPI interface acts as a bridge between the external microprocessor bus and System Bus. The MPI may work in an independent clock domain from the System Bus if the System Bus clock is not sourced from the external microprocessor clock. Pipelined operation allows high-speed memory interface to the EBR and peripheral access without the requirement for additional cycles on the bus. Burst transfers allow optimal use of the memory interface by giving advance information of the nature of the transfers.

Details for the majority of the peripherals can be found in the associated technical documentation, see details at the end of this data sheet. Additional details of the MPI are provided below.

Microprocessor Interface (MPI)

The LatticeSC family devices have a dedicated synchronous MPI function block. The MPI is programmable to operate with PowerPC/PowerQUICC MPC860/MPC8260 series microprocessors. The MPI implements an 8-, 16-, or 32-bit interface with 1-bit, 2-bit, or 4-bit parity to the host processor (PowerPC) that can be used for configuration and read-back of the FPGA as well as for user-defined data processing and general monitoring of FPGA functions.

The control portion of the MPI is available following power-up of the FPGA if the mode pins specify MPI mode, even if the FPGA is not yet configured. The width of the data port is selectable among 8-, 16-, or 32-bit and the parity bus can be 1-, 2-, or 4-bit. In configuration mode the data and parity bus width are related to the state of the M[0:3] mode pins. For post-configuration use, the MPI must be included in the configuration bit stream by using an MPI library element in your design from the ispLEVER primitive library, or by setting the bit of the MPI configuration control register prior to the start of configuration. The user can also enable and disable the parity bus through the configuration bit stream. These pads can be used as general I/O when they are not needed for MPI use.

The MPI block also provides the capability to interface directly to the FPGA fabric with a databus after configuration.The bus protocol is still handled by the MPI block but the direct FPGA access allows high-speed block data transfers such as DMA transactions. Figure 2-32 shows one of the ways a PowerPC is connected to MPI.

PURESPEED I/O Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input voltage		0	—	2.4	V
V_{THD}	Differential input threshold (Q-$\overline{Q}$)		+/-100	—	—	mV
V_{CM}	Input common mode voltage		0.05	1.2	2.35	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	0.9V	1.03	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 Ohm	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} - V_{OM})/2, R_T = 100 Ohm	1.125	1.20	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{SAB}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	12	mA
T_R, T_F	Output rise and fall times, 20% to 80%	—	—	500	ps	T_R, T_F

Notes:
1. Data is for 3.5mA differential current drive. Other differential driver current options are available.
2. If the low power mode of the input buffer is used, the minimum V_{CM} is 600 mV.

Mini-LVDS

Over Recommended Operating Conditions

Parameter Symbol	Description	Min.	Typ.	Max.	Units
Z_O	Single-ended PCB trace impedance	30	50	75	ohms
R_T	Differential termination resistance	60	100	150	ohms
V_{OD}	Output voltage, differential, $\|V_{OP} - V_{OM}\|$	300	—	600	mV
V_{OS}	Output voltage, common mode, $\|V_{OP} + V_{OM}\|/2$	1	1.2	1.4	V
ΔV_{OD}	Change in V_{OD}, between H and L	—	—	50	mV
ΔV_{ID}	Change in V_{OS}, between H and L	—	—	50	mV
V_{THD}	Input voltage, differential, $\|V_{INP} - V_{INM}\|$	200	—	600	mV
V_{CM}	Input voltage, common mode, $\|V_{INP} + V_{INM}\|/2$	0.3+(V_{THD}/2)	—	2.1-(V_{THD}/2)	
T_R, T_F	Output rise and fall times, 20% to 80%	—	—	500	ps
T_{ODUTY}	Output clock duty cycle	45	—	55	%
T_{IDUTY}	Input clock duty cycle	40	—	60	%

Note: Data is for 6mA differential current drive. Other differential driver current options are available.

sysCLOCK PLL Timing

Over Recommended Operating Conditions

Parameter	Description	Conditions	Min.	Typ	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		2	—	1000	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)		1.5625	—	1000	MHz
f_{VCO}	PLL VCO Frequency		100	—	1000	MHz
f_{PFD}	Phase Detector Input Frequency		2	—	700	MHz
AC Characteristics						
t_{DT}	Output Clock Duty Cycle	Default duty cycle selected (at 50% levels)	45	—	55	%
t_{OPJIT}[1]	Output Clock Period Jitter	2 MHz ≤ f_{PFD} ≤ 10 MHz	—	—	200	ps
		f_{PFD} > 10 MHz	—	—	100	ps
t_{CPJIT}[1]	Output Clock Cycle-to-Cycle Jitter		—	—	100	ps
t_{SKEW}	Output Clock-to-Clock Skew (Between Two Outputs with the Same Phase Setting)		—	—	20	ps
t_{LOCK}	PLL Lock-in Time		—	—	1	ms
t_{IPJIT}	Input Clock Period Jitter		—	—	±250	ps
t_{HI}	Input Clock High Time	At 80% level	350	—	—	ps
t_{LO}	Input Clock Low Time	At 20% level	350	—	—	ps
t_{RSWA}	Analog Reset Signal Pulse Width		100	—	—	ns
t_{RSWD}	Digital Reset Signal Pulse Width		3	—	—	ns
t_{DEL}	Timeshift Delay Step Size		40	80	120	ps
t_{RANGE}	Timeshift Delay Range		—	+/- 560	—	ps
f_{SS}	Spread Spectrum Modulation Frequency		30	—	500	KHz
% Spread	Percentage Downspread for SS Mode		0.5	—	1.5	%
	VCO Clock Phase Adjustment Accuracy		-5	—	5	°

1. Values are measured with FPGA logic active, no additional I/Os toggling and REFCLK total jitter = 30 ps

Switching Test Conditions

Figure 3-15 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3-4.

Figure 3-15. Output Test Load, LVTTL and LVCMOS Standards

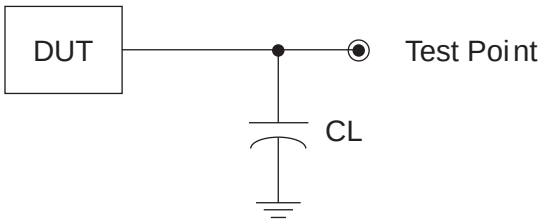


Table 3-4. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	C_L	Timing Ref.	V_T
LVTTL and other LVCMOS settings (L -> H, H -> L)	30pF	LVCMOS 3.3 = 1.5V	—
		LVCMOS 2.5 = $V_{CCIO}/2$	—
		LVCMOS 1.8 = $V_{CCIO}/2$	—
		LVCMOS 1.5 = $V_{CCIO}/2$	—
		LVCMOS 1.2 = $V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> H)	30pF	$V_{CCIO}/2$	V_{OL}
LVCMOS 2.5 I/O (Z -> L)		$V_{CCIO}/2$	V_{OH}
LVCMOS 2.5 I/O (H -> Z)		V_{OH} - 0.15	V_{OL}
LVCMOS 2.5 I/O (L -> Z)		V_{OL} + 0.15	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Signal Descriptions

Signal Name	I/O	Description
General Purpose		
P[Edge] [Row/Column Number*]_[A/B/C/D]	I/O	[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top). [Row/Column Number] indicates the PIC row or the column of the device on which the PIC exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number. [A/B/C/D] indicates the PIO within the PIC to which the pad is connected. Some of these user programmable pins are shared with special function pins. These pin when not used as special purpose pins can be programmed as I/Os for user logic. During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
VREF1_x, VREF2_x	—	The reference supply pins for I/O bank x. Any I/O pin in a bank can be assigned as a reference supply pin, but software defaults use designated pin.
NC	—	No connect. NC pins should not be connected to any active signals, VCC or GND.
Non-SERDES Power Supplies		
VCCIOx	—	VCCIO - The power supply pins for I/O bank x. Dedicated pins.
VCC12[1]	—	1.2V supply for configuration logic, PLLs and SERDES Rx, Tx and PLL. All VCC12 pins must be connected. As VCC12 supplies power for analog circuitry, VCC12 should be quiet and isolated from noisy digital board supplies.
VTT_x	—	Termination voltage for bank x. When VTT termination is not required, or used to provide the common mode termination voltage (VCMT), these pins can be left unconnected on the device. VCMT function is not used in the bank. If the internal or external VCMT function for differential input termination is used, the VTT pins should be unconnected and allowed to float.
GND	—	GND - Ground. Dedicated pins. All grounds must be electrically connected at the board level.
VCC	—	VCC - The power supply pins for core logic. Dedicated pins (1.2V/ 1.0V).
VCCAUX	—	VCCAUX - Auxiliary power supply pin - powers all differential and referenced input buffers. Dedicated pins (2.5V).
VCCJ	—	VCCJ - The power supply pin for JTAG Test Access Port.
PROBE_VCC	—	VCC signal - Connected to internal VCC node. Can be used for feedback to control an external board power converter. Can be unconnected if not used.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
MPI_STRBN	I	Driven active low indicates the start of a transaction on the PowerPC bus. MPI will strobe the address bus at next rising edge of clock.
MPI_ADDR[31:14]	I	Address bus driven by a PowerPC bus master. Only 18-bit width is needed. It has to be the least significant bit of the PowerPC 32-bit address A[31:14].
MPI_DAT[n:0]	I/O	Selectable data bus width from 8, and 16-bit. Driven by a bus master in a write transaction. Driven by MPI in a read transaction.
MPI_PAR[m:0]	I/O	Selectable parity bus width from 1, 2, and 3-bit. MPI_DP[0] for MPI_D[7:0], MPI_DP[1] for MPI_D[15:8] and MPI_DP[2] for MPI_D[23:16].
MPI_TA	O	Transfer acknowledge. Driven active low indicates that MPI received the data on the write cycle or returned data on the read cycle.
MPI_TEA	O	Transfer Error Acknowledge. Driven active low indicates that MPI detects a bus error on the internal system bus for current transaction.
MPI_RETRY	O	Active low MPI Retry requests the MPC860 to relinquish the bus and retry the cycle.
Multi-chip Alignment (User I/O if not used.)		
MCA_DONE_OUT	O	Multi-chip alignment done output (to second MCA chip)
MCA_DONE_IN	I	Multi-chip alignment done input (from second MCA chip)
MCA_CLK_P[1:2]_OUT	O	Multi-chip alignment clock [1:2] output (sourced by MCA master chip)
MCA_CLK_P[1:2]_IN	I	Multi-chip alignment clock [1:2] input (from MCA master chip
TEMP	—	Temperature sensing diode pin. Dedicated pin. Accuracy is typically +/- 10°C.
Miscellaneous Dedicated Pins		
XRES	—	External reference resistor between this pin and ground. The reference resistor is used to calibrate the programmable terminating resistors used in the I/Os. Dedicated pin. Value: 1K ± 1% ohm.
DIFFRx	—	Only used if a differential driver is used in a bank. This DIFFRx must be connected to ground via an external 1K ±1% ohm resistor for all banks that have a differential driver.
SERDES Block (Dedicated Pins)		
[A:D]_HDINPx_[L/R]	I	High-speed input (positive) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDINNx_[L/R]	I	High-speed input (negative) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDOUTPx_[L/R]	O	High-speed output (positive) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDOUTNx_[L/R]	O	High-speed output (negative) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_REFCLKP_[L/R]	I	Ref clock input (positive), aux channel on left [L] or right [R] side of device.
[A:D]_REFCLKN_[L/R]	I	Ref clock input (negative), aux channel on left [L] or right [R] side of device.

LFSC/M15 Logic Signal Connections: 256 fpBGA[1,2] (Cont.)

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
M4	PL43B	6	
P1	PL45A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E
R1	PL45B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E
R2	XRES	-	
P3	TEMP	6	
R3	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B
N4	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B
T3	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D
T2	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D
N5	PB5D	5	VREF1_5
P5	PB8A	5	
R5	PB8B	5	
T4	PB9A	5	
T5	PB9B	5	
R6	PB12A	5	PCLKT5_3
T6	PB12B	5	PCLKC5_3
L5	PB13C	5	
P6	PB15A	5	PCLKT5_0
T7	PB15B	5	PCLKC5_0
M7	PB15D	5	VREF2_5
R8	PB16A	5	PCLKT5_1
T8	PB16B	5	PCLKC5_1
N7	PB17A	5	PCLKT5_2
N8	PB17B	5	PCLKC5_2
R9	PB20A	5	
T9	PB20B	5	
M8	PB21A	5	
M9	PB21B	5	
P8	PB24A	5	
P9	PB24B	5	
T10	PB28A	4	
R11	PB28B	4	
N9	PB31A	4	
N10	PB31B	4	
T11	PB32A	4	
R12	PB32B	4	
P11	PB35A	4	PCLKT4_2
M10	PB35B	4	PCLKC4_2
T12	PB36A	4	PCLKT4_1
P12	PB36B	4	PCLKC4_1
T13	PB37A	4	PCLKT4_0
T14	PB37B	4	PCLKC4_0
R15	PB37C	4	VREF2_4

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
N3	PL27A	6		PL30A	6	
P3	PL27B	6		PL30B	6	
P4	PL27C	6	PCLKT6_3	PL30C	6	PCLKT6_3
P2	PL28A	6		PL31A	6	
R2	PL28B	6		PL31B	6	
T3	PL28C	6	PCLKT6_2	PL31C	6	PCLKT6_2
R3	PL28D	6	PCLKC6_2	PL31D	6	PCLKC6_2
P1	PL31A	6		PL34A	6	
R1	PL31B	6		PL34B	6	
R5	PL31C	6	VREF1_6	PL34C	6	VREF1_6
R4	PL31D	6		PL34D	6	
T2	PL32A	6		PL35A	6	
U2	PL32B	6		PL35B	6	
T1	PL33A	6		PL38A	6	
U1	PL33B	6		PL38B	6	
V1	PL35A	6		PL42A	6	
W1	PL35B	6		PL42B	6	
V6	PL35D	6	DIFFR_6	PL42D	6	DIFFR_6
V2	PL36A	6		PL43A	6	
W2	PL36B	6		PL43B	6	
Y1	PL37A	6		PL44A	6	
AA1	PL37B	6		PL44B	6	
AB1	PL39A	6		PL48A	6	
AC1	PL39B	6		PL48B	6	
Y5	PL40A	6		PL49A	6	
Y6	PL40B	6		PL49B	6	
AD2	PL41A	6		PL51A	6	
AE2	PL41B	6		PL51B	6	
AB5	PL41D	6	VREF2_6	PL51D	6	VREF2_6
AC3	PL43A	6		PL52A	6	
AD3	PL43B	6		PL52B	6	
AF1	PL44A	6		PL55A	6	
AG1	PL44B	6		PL55B	6	
AB6	PL44C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F	PL55C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F
AC5	PL44D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F	PL55D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F
AF2	PL45A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E	PL57A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E
AG2	PL45B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E	PL57B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E
AC6	PL45C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A	PL57C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A
AC7	PL45D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A	PL57D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A
AE4	XRES	-		XRES	-	
AG4	VCC12	-		VCC12	-	
AD5	TEMP	6		TEMP	6	
AF5	VCC12	-		VCC12	-	
AH1	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B
AJ1	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
B29	NC	-		NC	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).
2. The LatticeSC/M15 and LatticeSC/M25 in a 900-pin package supports a 16-bit MPI interface.

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
P10	GND	-		GND	-	
P13	GND	-		GND	-	
P15	GND	-		GND	-	
P18	GND	-		GND	-	
P20	GND	-		GND	-	
P24	GND	-		GND	-	
R12	GND	-		GND	-	
R14	GND	-		GND	-	
R16	GND	-		GND	-	
R17	GND	-		GND	-	
R19	GND	-		GND	-	
R21	GND	-		GND	-	
R26	GND	-		GND	-	
R6	GND	-		GND	-	
T15	GND	-		GND	-	
T18	GND	-		GND	-	
T30	GND	-		GND	-	
T4	GND	-		GND	-	
U15	GND	-		GND	-	
U18	GND	-		GND	-	
U29	GND	-		GND	-	
U3	GND	-		GND	-	
V12	GND	-		GND	-	
V14	GND	-		GND	-	
V16	GND	-		GND	-	
V17	GND	-		GND	-	
V19	GND	-		GND	-	
V21	GND	-		GND	-	
V27	GND	-		GND	-	
V7	GND	-		GND	-	
W13	GND	-		GND	-	
W15	GND	-		GND	-	
W18	GND	-		GND	-	
W20	GND	-		GND	-	
W23	GND	-		GND	-	
W9	GND	-		GND	-	
Y12	GND	-		GND	-	
Y14	GND	-		GND	-	
Y19	GND	-		GND	-	
Y21	GND	-		GND	-	
Y30	GND	-		GND	-	
Y4	GND	-		GND	-	
N13	VCC	-		VCC	-	
N15	VCC	-		VCC	-	
N16	VCC	-		VCC	-	
N17	VCC	-		VCC	-	
N18	VCC	-		VCC	-	
N20	VCC	-		VCC	-	
P14	VCC	-		VCC	-	
P16	VCC	-		VCC	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
K20	GND	-		GND	-	
K23	GND	-		GND	-	
K26	GND	-		GND	-	
K28	GND	-		GND	-	
K6	GND	-		GND	-	
K9	GND	-		GND	-	
L12	GND	-		GND	-	
L32	GND	-		GND	-	
L4	GND	-		GND	-	
M10	GND	-		GND	-	
M17	GND	-		GND	-	
M24	GND	-		GND	-	
N29	GND	-		GND	-	
N7	GND	-		GND	-	
P15	GND	-		GND	-	
P20	GND	-		GND	-	
P3	GND	-		GND	-	
P31	GND	-		GND	-	
R10	GND	-		GND	-	
R14	GND	-		GND	-	
R16	GND	-		GND	-	
R19	GND	-		GND	-	
R21	GND	-		GND	-	
R26	GND	-		GND	-	
T15	GND	-		GND	-	
T17	GND	-		GND	-	
T18	GND	-		GND	-	
T20	GND	-		GND	-	
T28	GND	-		GND	-	
T6	GND	-		GND	-	
U16	GND	-		GND	-	
U19	GND	-		GND	-	
U23	GND	-		GND	-	
U32	GND	-		GND	-	
U4	GND	-		GND	-	
V12	GND	-		GND	-	
V16	GND	-		GND	-	
V19	GND	-		GND	-	
V3	GND	-		GND	-	
V31	GND	-		GND	-	
W15	GND	-		GND	-	
W17	GND	-		GND	-	
W18	GND	-		GND	-	
W20	GND	-		GND	-	
W29	GND	-		GND	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
N27	PL47C	7	
P27	PL47D	7	
K33	PL49A	7	
L33	PL49B	7	
M30	PL49C	7	
N30	PL49D	7	
M31	PL51A	7	
N31	PL51B	7	
P24	PL51C	7	
R24	PL51D	7	
M33	PL56A	7	
N33	PL56B	7	
U25	PL56C	7	
T25	PL56D	7	
L34	PL57A	7	
M34	PL57B	7	
P29	PL57C	7	
R29	PL57D	7	
N34	PL60A	7	
P34	PL60B	7	
R27	PL60C	7	
T27	PL60D	7	
R32	PL61A	7	PCLKT7_1
R31	PL61B	7	PCLKC7_1
U24	PL61C	7	PCLKT7_3
T24	PL61D	7	PCLKC7_3
P33	PL62A	7	PCLKT7_0
R33	PL62B	7	PCLKC7_0
T26	PL62C	7	PCLKT7_2
U26	PL62D	7	PCLKC7_2
T32	PL64A	6	PCLKT6_0
T31	PL64B	6	PCLKC6_0
U29	PL64C	6	PCLKT6_1
V29	PL64D	6	PCLKC6_1
T30	PL65A	6	
U30	PL65B	6	
U27	PL65C	6	PCLKT6_3
V27	PL65D	6	PCLKC6_3
R34	PL66A	6	
T34	PL66B	6	
U28	PL66C	6	PCLKT6_2
V28	PL66D	6	PCLKC6_2
V30	PL69A	6	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AP20	PB61B	5	
AH21	PB61C	5	
AH20	PB61D	5	
AM20	PB63A	5	
AM19	PB63B	5	
AJ21	PB63C	5	
AJ20	PB63D	5	
AK19	PB66A	5	
AK18	PB66B	5	
AE18	PB66C	5	
AD18	PB66D	5	
AN19	PB69A	5	
AN18	PB69B	5	
AG18	PB69C	5	
AF18	PB69D	5	
AP19	PB71A	5	
AP18	PB71B	5	
AJ18	PB71C	5	
AH18	PB71D	5	
AP17	PB73A	4	
AP16	PB73B	4	
AJ17	PB73C	4	
AH17	PB73D	4	
AN17	PB75A	4	
AN16	PB75B	4	
AE17	PB75C	4	
AD17	PB75D	4	
AK17	PB78A	4	
AK16	PB78B	4	
AG17	PB78C	4	
AF17	PB78D	4	
AM16	PB81A	4	
AM15	PB81B	4	
AJ15	PB81C	4	
AJ14	PB81D	4	
AL16	PB83A	4	
AL15	PB83B	4	
AG16	PB83C	4	
AF16	PB83D	4	
AP15	PB86A	4	
AP14	PB86B	4	
AH15	PB86C	4	
AH14	PB86D	4	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AL4	PR117B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E
AL3	PR117A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E
AD10	PR116D	3	
AD9	PR116C	3	
AH4	PR116B	3	
AJ4	PR116A	3	
AK5	PR115D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F
AJ5	PR115C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F
AM1	PR115B	3	
AL1	PR115A	3	
AH5	PR112D	3	
AG5	PR112C	3	
AL2	PR112B	3	
AK2	PR112A	3	
AB9	PR109D	3	
AC9	PR109C	3	
AH1	PR109B	3	
AG1	PR109A	3	
AE8	PR107D	3	VREF2_3
AD8	PR107C	3	
AJ3	PR107B	3	
AH3	PR107A	3	
AD7	PR104D	3	
AC7	PR104C	3	
AJ2	PR104B	3	
AH2	PR104A	3	
AF6	PR103D	3	
AF5	PR103C	3	
AF4	PR103B	3	
AE4	PR103A	3	
AD6	PR99D	3	
AC6	PR99C	3	
AG2	PR99B	3	
AF2	PR99A	3	
AC8	PR98D	3	
AB8	PR98C	3	
AK1	PR98B	3	
AJ1	PR98A	3	
AB10	PR96D	3	
AA10	PR96C	3	
AF3	PR96B	3	
AE3	PR96A	3	
AE5	PR94D	3	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
F6	A_VDDOB0_R	-	
B4	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N
F7	A_VDDOB1_R	-	
B5	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N
E6	VCC12	-	
A5	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P
B6	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
A6	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
C6	VCC12	-	
D4	A_VDDIB1_R	-	
C7	VCC12	-	
D5	A_VDDIB2_R	-	
A7	A_HDINP2_R	-	PCS 3E0 CH 2 IN P
B7	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
E7	VCC12	-	
A8	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
F8	A_VDDOB2_R	-	
B8	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
F9	A_VDDOB3_R	-	
B9	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
E8	VCC12	-	
A9	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
B10	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
A10	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
C10	VCC12	-	
D6	A_VDDIB3_R	-	
G10	VCC12	-	
D7	B_VDDIB0_R	-	
E10	B_HDINP0_R	-	PCS 3E1 CH 0 IN P
F10	B_HDINN0_R	-	PCS 3E1 CH 0 IN N
K10	VCC12	-	
A11	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P
D10	B_VDDOB0_R	-	
B11	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N
D11	B_VDDOB1_R	-	
B12	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N
L10	VCC12	-	
A12	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P
F11	B_HDINN1_R	-	PCS 3E1 CH 1 IN N
E11	B_HDINP1_R	-	PCS 3E1 CH 1 IN P
G11	VCC12	-	
D8	B_VDDIB1_R	-	
G12	VCC12	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AD33	PL59D	6		PL73D	6	
AA38	PL60A	6		PL74A	6	
AB38	PL60B	6		PL74B	6	
AC29	PL60C	6		PL74C	6	
AD29	PL60D	6		PL74D	6	
AA41	PL61A	6		PL75A	6	
AB41	PL61B	6		PL75B	6	
AC34	PL61C	6		PL75C	6	
AD34	PL61D	6		PL75D	6	
AA42	PL63A	6		PL77A	6	
AB42	PL63B	6		PL77B	6	
AC37	PL63C	6		PL77C	6	
AD37	PL63D	6		PL77D	6	
AC38	PL64A	6		PL78A	6	
AD38	PL64B	6		PL78B	6	
AD36	PL64C	6		PL78C	6	
AE36	PL64D	6		PL78D	6	
AC39	PL65A	6		PL79A	6	
AD39	PL65B	6		PL79B	6	
AD35	PL65C	6		PL79C	6	
AE35	PL65D	6		PL79D	6	
AC40	PL67A	6		PL81A	6	
AD40	PL67B	6		PL81B	6	
AE37	PL67C	6		PL81C	6	
AF37	PL67D	6		PL81D	6	
AC41	PL68A	6		PL82A	6	
AD41	PL68B	6		PL82B	6	
AE34	PL68C	6		PL82C	6	
AF34	PL68D	6		PL82D	6	
AC42	PL69A	6		PL83A	6	
AD42	PL69B	6		PL83B	6	
AE33	PL69C	6		PL83C	6	
AF33	PL69D	6		PL83D	6	
AE38	PL72A	6		PL86A	6	
AF38	PL72B	6		PL86B	6	
AE32	PL72C	6		PL86C	6	
AF32	PL72D	6		PL86D	6	
AE41	PL73A	6		PL87A	6	
AF41	PL73B	6		PL87B	6	
AE31	PL73C	6		PL87C	6	
AF31	PL73D	6		PL87D	6	
AE42	PL74A	6		PL88A	6	
AF42	PL74B	6		PL88B	6	
AG37	PL74C	6		PL88C	6	
AH37	PL74D	6		PL88D	6	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
J1	PR25B	2		PR38B	2	
K1	PR25A	2		PR38A	2	
V12	PR24D	2		PR34D	2	
U12	PR24C	2		PR34C	2	
K2	PR24B	2		PR34B	2	
J2	PR24A	2		PR34A	2	
R10	PR22D	2		PR30D	2	
T10	PR22C	2		PR30C	2	
L5	PR22B	2		PR30B	2	
K5	PR22A	2		PR30A	2	
P9	PR21D	2		PR26D	2	
N9	PR21C	2		PR26C	2	
L6	PR21B	2		PR26B	2	
K6	PR21A	2		PR26A	2	
M8	PR20D	2		PR19D	2	
M9	PR20C	2		PR19C	2	
H1	PR20B	2		PR19B	2	
G1	PR20A	2		PR19A	2	
U14	PR18D	2	VREF2_2	PR18D	2	VREF2_2
T14	PR18C	2		PR18C	2	
H2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
G2	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
P10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
N10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
H3	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
G3	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
R11	PR16D	2		PR15D	2	
P11	PR16C	2		PR15C	2	
J5	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
J6	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
P18	VCCJ	-		VCCJ	-	
P19	TDO	-	TDO	TDO	-	TDO
R21	TMS	-		TMS	-	
P20	TCK	-		TCK	-	
P12	TDI	-		TDI	-	
P17	PROGRAMN	1		PROGRAMN	1	
P21	MPIIRQN	1	CFGIRQN/MPI_IRQ_N	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
P13	CCLK	1		CCLK	1	
H10	RESP_URC	-		RESP_URC	-	
N13	VCC12	-		VCC12	-	
H9	A_REFCLKN_R	-		A_REFCLKN_R	-	
G9	A_REFCLKP_R	-		A_REFCLKP_R	-	
F2	VCC12	-		VCC12	-	
H4	A_VDDIB0_R	-		A_VDDIB0_R	-	
C1	A_HDINP0_R	-	PCS 3E0 CH 0 IN P	A_HDINP0_R	-	PCS 3E0 CH 0 IN P

Date	Version	Section	Change Summary
December 2011	02.4	DC and Switching Characteristics	Updated JTAG Port Timing Specifications table.